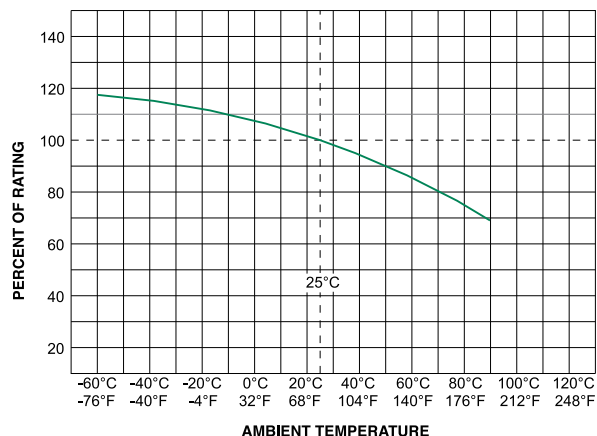
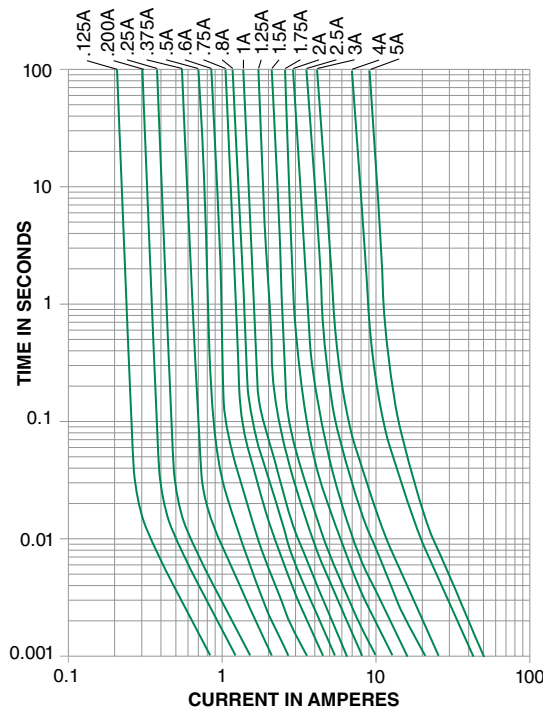


Temperature Derating Curve

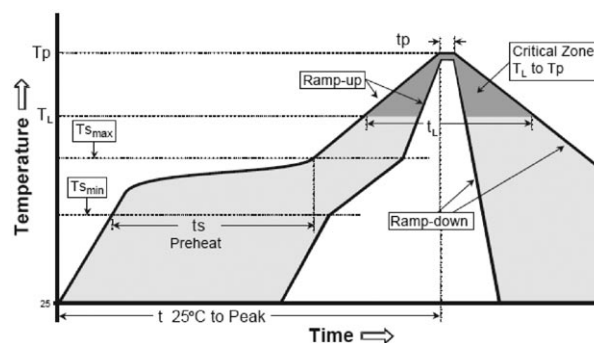


Average Time Current Curves



Soldering Parameters - Wave Soldering

Reflow Condition		Pb – Free assembly
Pre Heat	- Temperature Min ($T_{s(min)}$)	150°C
	- Temperature Max ($T_{s(max)}$)	200°C
	- Time (Min to Max) (t_s)	60 – 180 secs
Average ramp up rate (Liquidus Temp (T_L) to peak		5°C/second max
$T_{s(max)}$ to T_L - Ramp-up Rate		5°C/second max
Reflow	- Temperature (T_L) (Liquidus)	217°C
	- Temperature (t_L)	60 – 150 seconds
Peak Temperature (T_p)		250 ^{+0/-5} °C
Time within 5°C of actual peak Temperature (t_p)		20 – 40 seconds
Ramp-down Rate		5°C/second max
Time 25°C to peak Temperature (T_p)		8 minutes Max.
Do not exceed		260°C

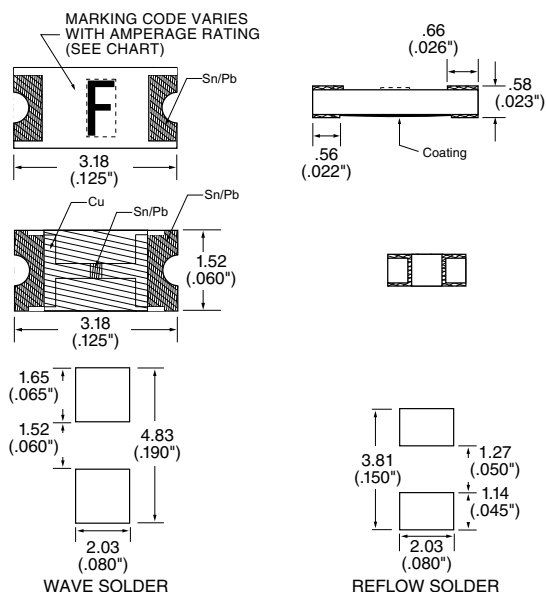


Product Characteristics

Materials	Body: Epoxy Substrate Terminations: 95% Tin / 5% Lead over Nickel over Copper Element Cover Coat: Conformal Coating
Operating Temperature	– 55°C to 90°C. Consult temperature derating curve chart.
Thermal Shock	Withstands 5 cycles of – 55°C to 125°C

Humidity	MIL-STD-202F Method 103B Condition D
Vibration	Per MIL-STD-202F, Method 201A
Insulation Resistance (After Opening)	Greater than 10,000 ohms.
Resistance to Soldering Heat	Withstands 60 seconds above 200°C and up to 260°C, maximum

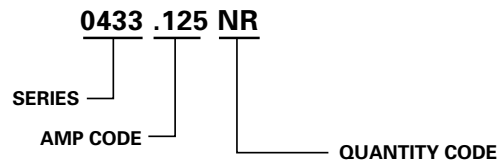
Dimensions



Part Marking System

Amp Code	Marking Code
.125	B
.200	C
.250	D
.375	E
.500	F
.600	.6
.750	G
.800	.8
001.	H
1.25	J
01.5	K
1.75	L
002.	N
02.5	O
003.	P
03.5	R
004.	S
005.	T

Part Numbering System



Packaging

Packaging Option	Packaging Specification	Quantity	Quantity & Packaging Code
Tape & Reel – 8mm tape	EIA RS-481-1 (IEC 286, part 3)	5000	NR